



SURFACE MOUNT ZENER DIODE

Features

- Planar Die Construction
- General Purpose, Medium Current
- Ideally Suited for Automated Assembly Processes
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Notes 2 and 6)

Mechanical Data

- Case: SOD-323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 2Ordering Information: See Page 2
- Weight: 0.004 grams (approximate)



Top View

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Forward Voltage	@ I _F = 10mA	V _F	0.9	V
Operating and Storage Temperature Range		T _J , T _{STG}	-65 to +150	°C

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3)	P _D	200	mW
Thermal Resistance, Junction to Ambient Air (Note 3)	$R_{ hetaJA}$	833	°C/W

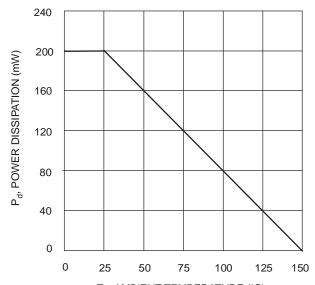
Electrical Characteristics @T_A = 25°C unless otherwise specified

Type Number	Marking Code (Note 4)	Zener Voltage Range (Note 3) Vz @ IzT		•	Maximum Zener Impedance (Note 5)		Maximum Reverse Current (Note 5)			
Number	(11016 4)			I _{ZT}	Z _{ZT} @ I _{ZT}	Z _{ZK} @ I _{ZK}	I _{ZK}	I _R	@ V _R	
		Nom (V)	Min (V)	Max (V)	mA	Ω)	mA	uA	٧
BZT52C51S	WW	51	48.0	54.0	5	100	750	1.0	0.1	38

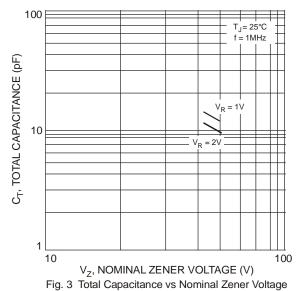
Notes:

- 1. No purposefully added lead. Halogen and Antimony Free.
- 2. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php
- 3. Short duration pulse test used to minimize self-heating effect.
- 4. When provided, otherwise, parts are provided with date code only, and type number identification appears on reel only.
- 5. f = 1kHz.
- 6. Product manufactured with Green Molding Compound and does not contain Halogens or Sb₂O₃ Fire Retardants.





 $\rm T_A, AMBIENT\ TEMPERATURE\ (^{\circ}C)$ Fig. 1 Power Dissipation vs Ambient Temperature



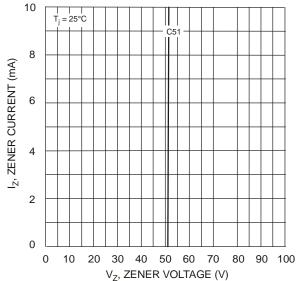


Fig. 2 Zener Breakdown Characteristics

Ordering Information (Note 7)

Part Number	Case	Packaging
BZT52C51S-7	SOD-323	3,000/Tape & Reel
BZT52C51S-13	SOD-323	10,000/Tape & Reel

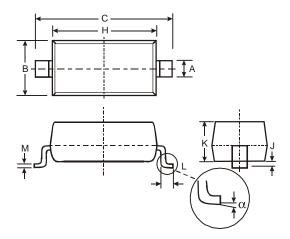
Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



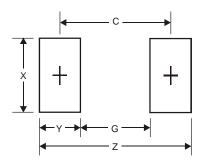


Package Outline Dimensions



SOD-323				
Dim	Min	Max		
Α	0.25	0.35		
В	1.20	1.40		
С	2.30	2.70		
Н	1.60	1.80		
J	0.00	0.10		
K	1.0	1.1		
L	0.20	0.40		
M	0.10	0.15		
α	0°	8°		
All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.75
G	1.05
Х	0.65
Y	1.35
С	2.40



IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
 - 1. are intended to implant into the body, or
 - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2009, Diodes Incorporated

www.diodes.com